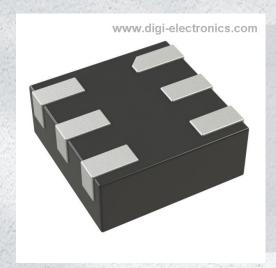


NLU1GT126CMUTCG Datasheet



https://www.DiGi-Electronics.com

DiGi Electronics Part Number NLU1GT126CMUTCG-DG

Manufacturer onsemi

Manufacturer Product Number NLU1GT126CMUTCG

Description IC BUFFER NON-INVERT 5.5V 6UDFN

Detailed Description Buffer, Non-Inverting 1 Element 1 Bit per Element 3

-State Output 6-UDFN (1x1)



Tel: +00 852-30501935

RFQ Email: Info@DiGi-Electronics.com

DiGi is a global authorized distributor of electronic components.



Purchase and inquiry

Manufacturer Product Number:	Manufacturer:
NLU1GT126CMUTCG	onsemi
Series:	Product Status:
MiniGate™	Active
Logic Type:	Number of Elements:
Buffer, Non-Inverting	1
Number of Bits per Element:	Input Type:
1	
Output Type:	Current - Output High, Low:
Output Type: 3-State	Current - Output High, Low: 8mA, 8mA
3-State	8mA, 8mA
3-State Voltage - Supply:	8mA, 8mA Operating Temperature:
3-State Voltage - Supply: 1.65V ~ 5.5V	8mA, 8mA Operating Temperature: -55°C ~ 125°C (TA)
3-State Voltage - Supply: 1.65V ~ 5.5V Mounting Type:	8mA, 8mA Operating Temperature: -55°C ~ 125°C (TA) Package / Case:

Environmental & Export classification

8542.39.0001

RoHS Status:	Moisture Sensitivity Level (MSL):
ROHS3 Compliant	1 (Unlimited)
REACH Status:	ECCN:
REACH Unaffected	EAR99
HTSUS:	

Non-Inverting 3-State Buffer, TTL Level

LSTTL-Compatible Inputs

The NLU1GT126 MiniGate[™] is an advanced CMOS high-speed non-inverting buffer in ultra-small footprint.

The NLU1GT126 requires the 3-state control input (OE) to be set Low to place the output in the high impedance state.

The device input is compatible with TTL-type input thresholds and the output has a full 5.0 V CMOS level output swing.

The NLU1GT126 input and output structures provide protection when voltages up to 7.0 V are applied, regardless of the supply voltage.

Features

- High Speed: $t_{PD} = 3.8 \text{ ns}$ (Typ) @ $V_{CC} = 5.0 \text{ V}$
- Low Power Dissipation: $I_{CC} = 2 \mu A$ (Max) at $T_A = 25^{\circ}C$
- TTL-Compatible Input: $V_{IL} = 0.8 \text{ V}$; $V_{IH} = 2.0 \text{ V}$
- CMOS-Compatible Output:
 - $V_{OH} > 0.8 V_{CC}$; $V_{OL} < 0.1 V_{CC}$ @ Load
- Power Down Protection Provided on inputs
- Balanced Propagation Delays
- Ultra-Small Packages
- These are Pb-Free Devices

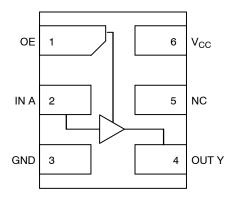


Figure 1. Pinout (Top View)

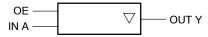


Figure 2. Logic Symbol

FUNCTION TABLE

Inp	Output	
Α	OE	Y
L	Н	L
Н	Н	H
X	L	Z

PIN ASSIGNMENT

1	OE
2	IN A
3	GND
4	OUT Y
5	NC
6	V _{CC}



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MARKING DIAGRAMS



UDFN6 1.2 x 1.0 CASE 517AA





UDFN6 1.0 x 1.0 CASE 517BX





UDFN6 1.45 x 1.0 CASE 517AQ



9 = Device Marking M = Date Code

ORDERING INFORMATION

See detailed ordering and shipping information on page 4 of this data sheet.

MAXIMUM RATINGS

Symbol	Parameter	Parameter			
V _{CC}	DC Supply Voltage		-0.5 to +7.0	V	
V _{IN}	DC Input Voltage		-0.5 to +7.0	V	
V _{OUT}	DC Output Voltage		-0.5 to +7.0	V	
I _{IK}	DC Input Diode Current V _{IN}	< GND	-20	mA	
I _{OK}	DC Output Diode Current V _{OUT}	< GND	±20	mA	
ΙO	DC Output Source/Sink Current		±12.5	mA	
I _{CC}	DC Supply Current Per Supply Pin		±25	mA	
I _{GND}	DC Ground Current per Ground Pin		±25	mA	
T _{STG}	Storage Temperature Range		-65 to +150	°C	
TL	Lead Temperature, 1 mm from Case for 10 Seconds		260	°C	
TJ	Junction Temperature Under Bias		150	°C	
MSL	Moisture Sensitivity		Level 1		
F _R	Flammability Rating Oxygen Index: 2	8 to 34	UL 94 V-0 @ 0.125 in		
I _{LATCHUP}	Latchup Performance Above V _{CC} and Below GND at 125°C (Not	te 2)	±500	mA	

Stresses exceeding those listed in the Maximum Ratings table may damage the device. If any of these limits are exceeded, device functionality should not be assumed, damage may occur and reliability may be affected.

1. Measured with minimum pad spacing on an FR4 board, using 10 mm-by-1 inch, 2 ounce copper trace no air flow.

RECOMMENDED OPERATING CONDITIONS

Symbol	Parameter	Min	Max	Unit
V _{CC}	Positive DC Supply Voltage	1.65	5.5	V
V_{IN}	Digital Input Voltage	0	5.5	V
V _{OUT}	Output Voltage	0	5.5	V
T _A	Operating Free-Air Temperature	-55	+125	°C
Δt/ΔV	Input Transition Rise or Fall Rate $ V_{CC} = 3.3 \text{ V} \pm 0.3 \text{ V} $	0	100 20	ns/V

Functional operation above the stresses listed in the Recommended Operating Ranges is not implied. Extended exposure to stresses beyond the Recommended Operating Ranges limits may affect device reliability.

^{2.} Tested to EIA / JESD78.

DC ELECTRICAL CHARACTERISTICS

				т	_ _A = 25 °	°C	T _A = -	+85°C	_ ~	-55°C 25°C	
Symbol	Parameter	Conditions	V _{CC} (V)	Min	Тур	Max	Min	Max	Min	Max	Unit
V _{IH}	Low-Level Input Voltage		3.0 4.5 to 5.5	1.4 2.0			1.4 2.0		1.4 2.0		V
V _{IL}	Low-Level Input Voltage		3.0 4.5 to 5.5			0.53 0.8		0.53 0.8		0.53 0.8	V
V _{OH}	High-Level Output Voltage	$V_{IN} = V_{IH} \text{ or } V_{IL}$ $I_{OH} = -50 \mu A$	3.0 4.5	2.9 4.4	3.0 4.5		2.9 4.4		2.9 4.4		V
		$V_{IN} = V_{IH} \text{ or } V_{IL}$ $I_{OH} = -4 \text{ mA}$ $I_{OH} = -8 \text{ mA}$	3.0 4.5	2.58 3.94			2.48 3.80		2.34 3.66		
V _{OL}	Low-Level Output Voltage	$V_{IN} = V_{IH} \text{ or } V_{IL}$ $I_{OL} = 50 \mu A$	3.0 4.5		0 0	0.1 0.1		0.1 0.1		0.1 0.1	V
		$V_{IN} = V_{IH} \text{ or } V_{IL}$ $I_{OL} = 4 \text{ mA}$ $I_{OL} = 8 \text{ mA}$	3.0 4.5			0.36 0.36		0.44 0.44		0.52 0.52	
I _{IN}	Input Leakage Current	$0 \le V_{IN} \le 5.5 V$	0 to 5.5			±0.1		±1.0		±1.0	μΑ
I _{CC}	Quiescent Supply Current	$0 \le V_{IN} \le V_{CC}$	5.5			1.0		20		40	μΑ
I _{CCT}	Quiescent Supply Current	V _{IN} = 3.4 V Other Input: V _{CC} or GND	5.5			1.35		1.50		1.65	mA
I _{OPD}	Output Leakage Current	V _{OUT} = 5.5 V	0			0.5		5.0		10	μΑ
I _{OZ}	3-State Leakage Current	$V_{IN} = V_{IH} \text{ or } V_{IL}$ $V_{OUT} = V_{CC} \text{ or }$ GND	0			±0.25		±2.5		±2.5	μΑ

Product parametric performance is indicated in the Electrical Characteristics for the listed test conditions, unless otherwise noted. Product performance may not be indicated by the Electrical Characteristics if operated under different conditions.

AC ELECTRICAL CHARACTERISTICS (Input $t_{r} = t_{f} = 3.0 \text{ ns}$)

		V _{CC}	Test	т	A = 25 °	°C	T _A =	+85°C		–55°C I25°C	
Symbol	Parameter	(V)	Condition	Min	Тур	Max	Min	Max	Min	Max	Unit
t _{PLH} , t _{PHL}	Propagation Delay, A to Y (Figures 3 and 5)	3.0 to 3.6	C _L = 15 pF C _L = 50 pF		5.6 8.1	8.0 11.5	1.0 1.0	9.5 13		12 16	ns
		4.5 to 5.5	C _L = 15 pF C _L = 50 pF		3.8 5.3	5.5 7.5	1.0 1.0	6.5 8.5		8.5 10.5	
t _{PZL} , t _{PZH}	Output Enable Time, OE to Y (Figures 4 and 6)	3.0 to 3.6	C _L = 15 pF C _L = 50 pF		5.4 7.9	8.0 11.5	1.0 1.0	9.5 13		11.5 15	ns
		4.5 to 5.5	C _L = 15 pF C _L = 50 pF		3.6 5.1	5.1 7.1	1.0 1.0	6.0 8.0		7.5 9.5	
t _{PLZ} , t _{PHZ}	Output Disable Time, OE to Y (Figures 4 and 6)	3.0 to 3.6	C _L = 15 pF C _L = 50 pF		6.5 8.0	9.7 13.2	1.0 1.0	11.5 15		14.5 18.5	ns
		4.5 to 5.5	C _L = 15 pF C _L = 50 pF		4.8 7.0	6.8 8.8	1.0 1.0	8.0 10		10 12	
C _{IN}	Input Capacitance				4	10		10		10	pF
C _{OUT}	3-State Output Capacitance (Output in High Impedance State)				6						pF
C _{PD}	Power Dissipation Capacitance (Note 3)	5.0			14						pF

^{3.} C_{PD} is defined as the value of the internal equivalent capacitance which is calculated from the dynamic operating current consumption without load. Average operating current can be obtained by the equation $I_{CC(OPR)} = C_{PD} \cdot V_{CC} \cdot f_{in} + I_{CC}$. C_{PD} is used to determine the no–load dynamic power consumption: $P_D = C_{PD} \cdot V_{CC}^2 \cdot f_{in} + I_{CC} \cdot V_{CC}$.

SWITCHING WAVEFORMS

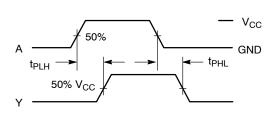
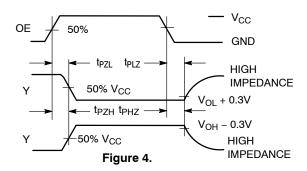
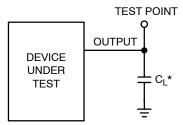
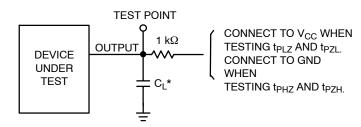


Figure 3. Switching Waveforms





*Includes all probe and jig capacitance



*Includes all probe and jig capacitance

Figure 5. Test Circuit

Figure 6. Test Circuit

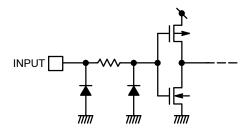


Figure 7. Input Equivalent Circuit

ORDERING INFORMATION

Device	Package	Shipping [†]
NLU1GT126MUTCG	UDFN6, 1.2 x 1.0, 0.4P (Pb-Free)	3000 / Tape & Reel
NLU1GT126AMUTCG	UDFN6, 1.45 x 1.0, 0.5P (Pb-Free)	3000 / Tape & Reel
NLU1GT126CMUTCG	UDFN6, 1.0 x 1.0, 0.35P (Pb-Free)	3000 / Tape & Reel

[†]For information on tape and reel specifications, including part orientation and tape sizes, please refer to our Tape and Reel Packaging Specifications Brochure, BRD8011/D.



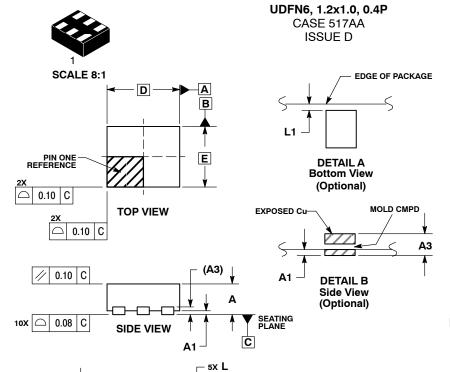
6X **b**

0.10 | C | A | B

0.05 C

NOTE 3

MECHANICAL CASE OUTLINE PACKAGE DIMENSIONS



е

BOTTOM VIEW

DATE 03 SEP 2010

NOTES

- DIMENSIONING AND TOLERANCING PER
 ASME Y14 5M 1994
- ASME Y14.5M, 1994.
 2. CONTROLLING DIMENSION: MILLIMETERS.
- DIMENSION 6 APPLIES TO PLATED TERMINAL AND IS MEASURED BETWEEN 0.25 AND 0.30 mm FROM TERMINAL.
 COPLANARITY APPLIES TO THE EXPOSED
- COPLANARITY APPLIES TO THE EXPOSED PAD AS WELL AS THE TERMINALS.

		MILLIMETERS				
L	DIM	MIN	MAX			
	Α	0.45	0.55			
	A1	0.00	0.05			
	АЗ	0.127	REF			
	b	0.15	0.25			
	D	1.20	BSC			
	Е	1.00	BSC			
	е	0.40	BSC			
	L	0.30	0.40			
	L1	0.00	0.15			
Г	L2	0.40	0.50			

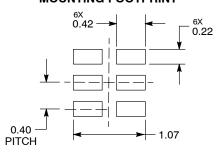
GENERIC MARKING DIAGRAM*



X = Specific Device CodeM = Date Code

*This information is generic. Please refer to device data sheet for actual part marking. Pb-Free indicator, "G" or microdot "■", may or may not be present.

MOUNTING FOOTPRINT*



DIMENSIONS: MILLIMETERS

*For additional information on our Pb-Free strategy and soldering details, please download the ON Semiconductor Soldering and Mounting Techniques Reference Manual, SOLDERRM/D.

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DESCRIPTION:	6 PIN UDFN, 1.2X1.0, 0.4P		PAGE 1 OF 1

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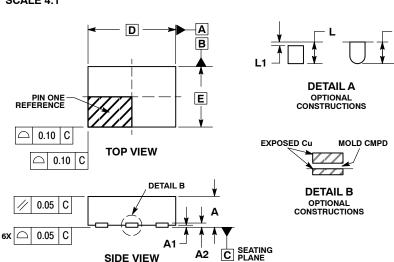


MECHANICAL CASE OUTLINE

PACKAGE DIMENSIONS



DATE 15 MAY 2008



6X L

6X b

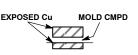
Ф

0.10

CAB

0.05 C NOTE 3

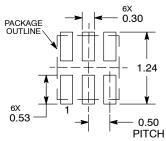




- NOTES:
 1. DIMENSIONING AND TOLERANCING PER ASME Y14.5M, 1994. CONTROLLING DIMENSION: MILLIMETERS.
- DIMENSION b APPLIES TO PLATED TERMINAL AND IS MEASURED BETWEEN 0.15 AND 0.30 mm FROM THE TERMINAL TIP.

	MILLIMETERS					
DIM	MIN MAX					
Α	0.45	0.55				
A1	0.00	0.05				
A2	0.07 REF					
b	0.20	0.30				
D	1.45	BSC				
Е	1.00	BSC				
Ф	0.50 BSC					
L	0.30	0.40				
L1		0.15				

MOUNTING FOOTPRINT



DIMENSIONS: MILLIMETERS

GENERIC MARKING DIAGRAM*

BOTTOM VIEW

е



Χ = Specific Device Code

*This information is generic. Please refer to device data sheet for actual part marking. Pb-Free indicator, "G" or microdot " ■", may or may not be present.

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^{*}For additional information on our Pb-Free strategy and soldering details, please download the **onsemi** Soldering and Mounting Techniques Reference Manual, SOLDERRM/D.



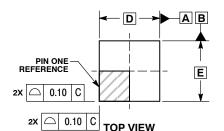
MECHANICAL CASE OUTLINE

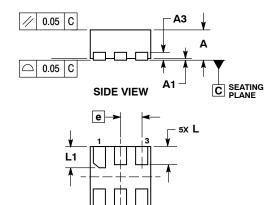
PACKAGE DIMENSIONS



UDFN6, 1x1, 0.35P CASE 517BX **ISSUE O**

DATE 18 MAY 2011





0.10 M C A B

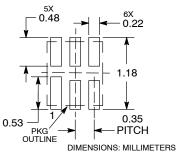
0.05 M C NOTE 3

NOTES:

- 1. DIMENSIONING AND TOLERANCING PER ASME Y14.5M, 1994.
- CONTROLLING DIMENSION: MILLIMETERS. DIMENSION b APPLIES TO PLATED TERMINAL AND IS MEASURED BETWEEN 0.15 AND 0.20 MM FROM TERMINAL TIP. 4. PACKAGE DIMENSIONS EXCLUSIVE OF
- BURRS AND MOLD FLASH.

	MILLIMETERS			
DIM	MIN	MAX		
Α	0.45	0.55		
A1	0.00	0.05		
A3	0.13 REF			
b	0.12	0.22		
D	1.00 BSC			
E	1.00 BSC			
е	0.35 BSC			
L	0.25	0.35		
L1	0.30	0.40		

RECOMMENDED **SOLDERING FOOTPRINT***



*For additional information on our Pb-Free strategy and soldering details, please download the onsemi Soldering and Mounting Techniques Reference Manual, SOLDERRM/D.

GENERIC MARKING DIAGRAM*

BOTTOM VIEW



X = Specific Device Code

M = Date Code

*This information is generic. Please refer to device data sheet for actual part marking. Pb-Free indicator, "G" or microdot "■", may or may not be present. Some products may not follow the Generic Marking.

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